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Harry D. Foster, Mentor Graphics Corp.

Session 8-C Tree Optimization in Physical Synthesis
Moderator(s): Joseph Shinnerl – Mentor Graphics Corp.
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8-C.1 Depth Controlled Symmetric Function Fanin Tree Restructure
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Chih-Cheng Hsu, National Chung Cheng University; Yu-Chuan Chen, National Chung Cheng University; Mark Po-Hung Lin, National Chung Cheng University

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Samuel I. Ward, University of Texas at Austin; Natarajan Viswanathan, IBM Research - Austin; Nancy Y. Zhou, IBM Research - Austin; Cliff C.N. Sze, IBM Research - Austin; Zhuo Li, IBM Research - Austin; Charles J. Alpert, IBM Research - Austin; David Z. Pan, University of Texas at Austin
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**Moderator(s): Evangeline Young – Chinese University of Hong Kong**
**Hsiao-Chun Huang – Nanyang Technological University**

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**Moderator(s): Yosinori Watanabe – Cadence Design Systems, Inc.**
**Younghyun Kim – Seoul National University**

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Karthick N. Parashar, INRIA Rennes - Bretagne Atlantique; Daniel Menard, Institut National des Sciences; Olivier Sentieys, INRIA Rennes - Bretagne Atlantique

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**Moderator(s): Miroslav N. Velev – Aries Design Automation, LLC**

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Kosuke Oshima, University of Tokyo; Takeshi Matsumoto, University of Tokyo; Masahiro Fujita, University of Tokyo

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Chun-Nan Chou, National Taiwan University; Chen-Kai Chu, National Taiwan University; Chung-Yang Huang, National Taiwan University

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Moderator(s): Lars Hagen – Cadence Design Systems, Inc.
Thorlindur Thorolfsson – Synopsys, Inc.

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Heechun Park, Seoul National University; Taewhan Kim, Seoul National University

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Wen-Pin Tu, Chung Yuan Christian University; Chung-Han Chou, National Tsing Hua University; Shih-Hsu Huang, Chung Yuan Christian University; Shih-Chieh Chang, National Tsing Hua University; Yow-Tyng Nieh, Industrial Technology Research Institute; Chien-Yung Chou, Industrial Technology Research Institute

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Moderator(s): Janet Roveda – University of Arizona
Organizer(s): Janet Roveda – University of Arizona

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